

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6129756

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT	
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT	
<b>CONVEYING PARTY DATA</b>		
	<b>Name</b>	<b>Execution Date</b>
	ARTHUR CHARLES KWUN	05/28/2020
	SO MORIMOTO	05/28/2020
<b>RECEIVING PARTY DATA</b>		
<b>Name:</b>	SONY INTERACTIVE ENTERTAINMENT INC.	
<b>Street Address:</b>	1-7-1 KONAN	
<b>Internal Address:</b>	MINATO-KU	
<b>City:</b>	TOKYO	
<b>State/Country:</b>	JAPAN	
<b>Postal Code:</b>	108-0075	
<b>PROPERTY NUMBERS Total: 1</b>		
<b>Property Type</b>	<b>Number</b>	
<b>Application Number:</b>	16887269	
<b>CORRESPONDENCE DATA</b>		
<b>Fax Number:</b>		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
<b>Phone:</b>	6193388075	
<b>Email:</b>	Noelle@rogitz.com	
<b>Correspondent Name:</b>	ROGITZ & ASSOCIATES	
<b>Address Line 1:</b>	4420 HOTEL CIRCLE COURT	
<b>Address Line 2:</b>	SUITE 230	
<b>Address Line 4:</b>	SAN DIEGO, CALIFORNIA 92108	
<b>ATTORNEY DOCKET NUMBER:</b>	SCEA20025US00	
<b>NAME OF SUBMITTER:</b>	JOHN L. ROGITZ	
<b>SIGNATURE:</b>	/John L. Rogitz/	
<b>DATE SIGNED:</b>	05/29/2020	
<b>Total Attachments: 4</b>		
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source=SCEA20025US00-Assignment#page2.tif		
source=SCEA20025US00-Assignment#page3.tif		



Docket No. SCEA20025US00

### ASSIGNMENT

WHEREAS, I, as a below named inventor, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in HEADSET MECHANISM FOR COMFORT COUPLING EAR CUPS TO HEAD for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name;

AND WHEREAS, Sony Interactive Entertainment Inc., a Japanese corporation having a place of business at 1-7-1 Konan, Minato-ku, Tokyo 108-0075 JAPAN (hereinafter referenced as ASSIGNEE(S)) is desirous of securing all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefore in the United States and in any and all foreign countries;

NOW THEREFORE, in return for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and any foreign countries, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America or any foreign country adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and foreign countries, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEES, as the assignees of the whole right, title and interest thereto;

I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or its designee, as ASSIGNEES or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and foreign countries;

I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEES thereof shall hereafter require and prepare at their own expense;

I further agree that ASSIGNEES will, upon their request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with or impact in any way this assignment and sale;

I agree that all my obligations hereunder shall survive any termination of my employment and shall be binding on my heirs, executors, administrators, or other legal representatives or assigns;

And I hereby authorize and request my attorney(s) of record in this application to insert the execution date, serial number and filing date of this document in the spaces that follow:

Serial Number: \_\_\_\_\_, Filing Date: \_\_\_\_\_

PATENT

REEL: 052792 FRAME: 0513

**Docket No. SCEA20025US00**

This assignment is executed on the date indicated below.

/Arthur Charles Kwun/

ARTHUR CHARLES KWUN

Dated: 5/28/2020

SO MORIMOTO

Dated: \_\_\_\_\_

**PATENT**

**REEL: 052792 FRAME: 0514**

Docket No. SCEA20025US00**ASSIGNMENT**

**WHEREAS, I**, as a below named inventor, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in **HEADSET MECHANISM FOR COMFORT COUPLING EAR CUPS TO HEAD** for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name;

**AND WHEREAS**, Sony Interactive Entertainment Inc., a Japanese corporation having a place of business at 1-7-1 Konan, Minato-ku, Tokyo 108-0075 JAPAN (hereinafter referenced as ASSIGNEE(S)) is desirous of securing all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefore in the United States and in any and all foreign countries;

**NOW THEREFORE**, in return for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and any foreign countries, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America or any foreign country adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and foreign countries, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEES, as the assignees of the whole right, title and interest thereto;

I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or its designee, as ASSIGNEES or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and foreign countries;

I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEES thereof shall hereafter require and prepare at their own expense;

I further agree that ASSIGNEES will, upon their request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with or impact in any way this assignment and sale;

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And I hereby authorize and request my attorney(s) of record in this application to insert the execution date, serial number and filing date of this document in the spaces that follow:

Serial Number: \_\_\_\_\_, Filing Date: \_\_\_\_\_

**PATENT****REEL: 052792 FRAME: 0515**

**Docket No. SCEA20025US00**

This assignment is executed on the date indicated below.

\_\_\_\_\_  
ARTHUR CHARLES KWUN

Dated: \_\_\_\_\_

\_\_\_\_\_  
/SoMorimoto/

SO MORIMOTO

Dated: 5/28/2020